The Tiva C Series TM4C123G LaunchPad Evaluation Kit (EK-TM4C123GXL) is a low-cost evaluation platform for ARM® Cortex™-M4F based microcontrollers. The Tiva C Series LaunchPad design highlights the TM4C123GH6 microcontroller’s USB 2.0 Device interface, Hibernation module, Motion Control PWMs and overall cost effectiveness. The Tiva C Series LaunchPad also features programmable user buttons and an RGB LED for custom applications. The stackable headers of the Tiva C Series TM4C123G LaunchPad BoosterPack XL interface demonstrate how easy it is to expand the functionality of the C Series LaunchPad when interfacing to other peripherals with MSP430™ and other TI MCU BoosterPacks.

**Kit contents**
- Tiva C Series LaunchPad Evaluation Kit (EK-TM4C123GXL)
- On-board In-Circuit Debug Interface (ICDI)
- USB Micro-B plug to USB-A plug cable
- README First document

For a complete list of available BoosterPacks that can be used with the Tiva C Series LaunchPad, see: [www.ti.com/tm4c123g-launchpad](http://www.ti.com/tm4c123g-launchpad)

**Features**
- Tiva C Series TM4C123GH6 microcontroller
- USB Micro-AB connector
  - Device mode default configuration
  - Host/OTG modes supportable
- RGB user LED
- Two user switches (application/wake)
- Available I/O brought out to headers on a 0.1” grid
- On-board In-Circuit Debug Interface (ICDI)
- Switch-selectable power sources
  - ICDI
  - USB Device
- Reset switch
- Preloaded RGB quickstart application
- Supported by TivaWare™ for C Series software including the USB library and the peripheral driver library
- Tiva C Series TM4C123G LaunchPad BoosterPack XL interface which features stackable headers to expand the capabilities of the 40-pin Tiva C Series LaunchPad evaluation platform.

![The 40-pin Tiva C Series LaunchPad also features stackable headers.](image-url)

![Tiva C Series TM4C123G LaunchPad evaluation kit](image-url)
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